Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A cover tape for tape-packaging electronic components, for heat-sealing a carrier tape storing therein electronic components, comprising:

a substrate film layer;

a soft material layer; and

a thermal adhesive layer; wherein

the soft material layer is formed of metallocene linear low-density polyethylene; and

the metallocene linear low-density polyethylene has a specific gravity in a range of from 0.888 to 0.907.

2. (Original) The cover tape for tape-packaging electronic components according to claim 1, wherein

the metallocene linear low-density polyethylene has a specific gravity in a range of from 0.892 to 0.907.

3. (Original) A cover tape for tape-packaging electronic components, for heat-sealing a carrier tape storing therein electronic components, comprising:

a substrate film layer;

a soft material layer; and

a thermal adhesive layer; wherein

the soft material layer is formed of metallocene linear low-density polyethylene; and

a softening temperature of the metallocene liner low-density polyethylene measured by a TMA method defined in JIS K7196 is in a range of from 75°C to 97°C.

4. (Original) The cover tape for tape-packaging electronic components according to claim 1, wherein

a softening temperature of the metallocene linear low-density polyethylene measured by a TMA method defined in JIS K7196 is in a range of from 75°C to 97°C.

5. (Currently Amended) The cover tape for tape-packaging electronic components according to ~~any one of claims 1 to 4~~claim 1, wherein

in a case where the thermal adhesive layer heat-seals the carrier tape, the thermal adhesive layer and the soft material layer are separated from each other in the heat-sealed area upon a peeling operation of the cover tape for tape-packaging electronic components from the carrier tape;

a peeling strength upon separation of the soft material layer from the thermal adhesive layer is in a range of from 0.1 N/mm width to 1.3 N/mm width, and

a difference between a maximum value of the peeling strength upon separation of the soft material layer from the thermal adhesive layer and a minimum value thereof is equal to or less than 0.3 N/mm width.

6. (New) The cover tape for tape-packaging electronic components according to claim 2, wherein

in a case where the thermal adhesive layer heat-seals the carrier tape, the thermal adhesive layer and the soft material layer are separated from each other in the heat-sealed area

upon a peeling operation of the cover tape for tape-packaging electronic components from the carrier tape;

a peeling strength upon separation of the soft material layer from the thermal adhesive layer is in a range of from 0.1 N/mm width to 1.3 N/mm width, and

a difference between a maximum value of the peeling strength upon separation of the soft material layer from the thermal adhesive layer and a minimum value thereof is equal to or less than 0.3 N/mm width.

7. (New) The cover tape for tape-packaging electronic components according to claim 3, wherein

in a case where the thermal adhesive layer heat-seals the carrier tape, the thermal adhesive layer and the soft material layer are separated from each other in the heat-sealed area upon a peeling operation of the cover tape for tape-packaging electronic components from the carrier tape;

a peeling strength upon separation of the soft material layer from the thermal adhesive layer is in a range of from 0.1 N/mm width to 1.3 N/mm width, and

a difference between a maximum value of the peeling strength upon separation of the soft material layer from the thermal adhesive layer and a minimum value thereof is equal to or less than 0.3 N/mm width.

8. (New) The cover tape for tape-packaging electronic components according to claim 4, wherein

in a case where the thermal adhesive layer heat-seals the carrier tape, the thermal adhesive layer and the soft material layer are separated from each other in the heat-sealed area

upon a peeling operation of the cover tape for tape-packaging electronic components from the carrier tape;

a peeling strength upon separation of the soft material layer from the thermal adhesive layer is in a range of from 0.1 N/mm width to 1.3 N/mm width, and

a difference between a maximum value of the peeling strength upon separation of the soft material layer from the thermal adhesive layer and a minimum value thereof is equal to or less than 0.3 N/mm width.